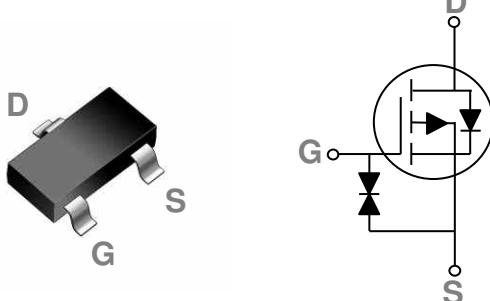


General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

SOT23-S Pin Configuration



BVDSS	RDSON	ID
-30V	950mΩ	-0.9A

Features

- -30V, -0.9A, $RDS(ON) = 950m\Omega @ VGS = -4.5V$
- Improved dv/dt capability
- Fast switching
- Green Device Available
- Suit for -1.5V Gate Drive Applications

Applications

- Notebook
- Load Switch
- Battery Protection
- Hand-held Instruments

Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 12	V
I_D	Drain Current – Continuous ($T_A=25^\circ C$)	-0.9	A
	Drain Current – Continuous ($T_A=70^\circ C$)	-0.7	A
I_{DM}	Drain Current – Pulsed ¹	-3.6	A
P_D	Power Dissipation ($T_A=25^\circ C$)	1.56	W
	Power Dissipation – Derate above 25°C	12.5	mW/°C
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	80	°C/W

Electrical Characteristics ($T_J=25\text{ }^\circ\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=-250\mu\text{A}$	-30	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to $25\text{ }^\circ\text{C}$, $I_D=-1\text{mA}$	---	-0.015	---	V/C
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=-30\text{V}$, $V_{GS}=0\text{V}$, $T_J=25\text{ }^\circ\text{C}$	---	---	-1	μA
		$V_{DS}=-24\text{V}$, $V_{GS}=0\text{V}$, $T_J=125\text{ }^\circ\text{C}$	---	---	-10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 12\text{V}$, $V_{DS}=0\text{V}$	---	---	± 40	μA

On Characteristics

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=-4.5\text{V}$, $I_D=-0.4\text{A}$	---	755	950	$\text{m}\Omega$
		$V_{GS}=-2.5\text{V}$, $I_D=-0.3\text{A}$	---	1170	1600	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=-250\mu\text{A}$	-0.5	-0.7	-1.2	V
			---	-1.78	---	
g_{fs}	Forward Transconductance	$V_{DS}=-4\text{V}$, $I_D=-0.4\text{A}$	---	0.8	---	S

Dynamic and switching Characteristics

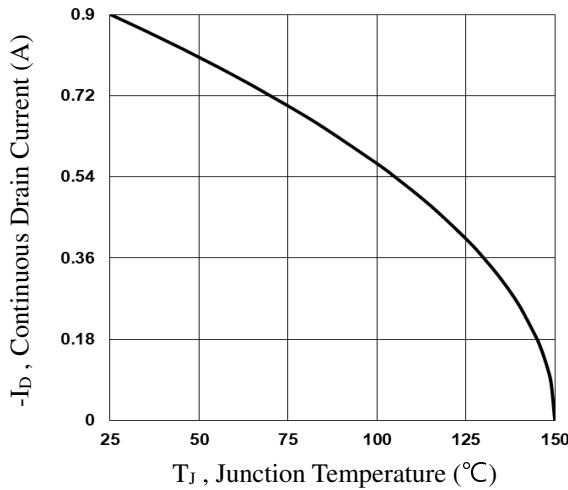
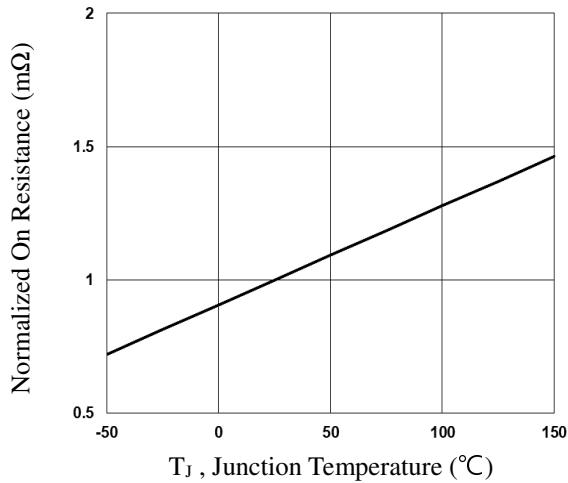
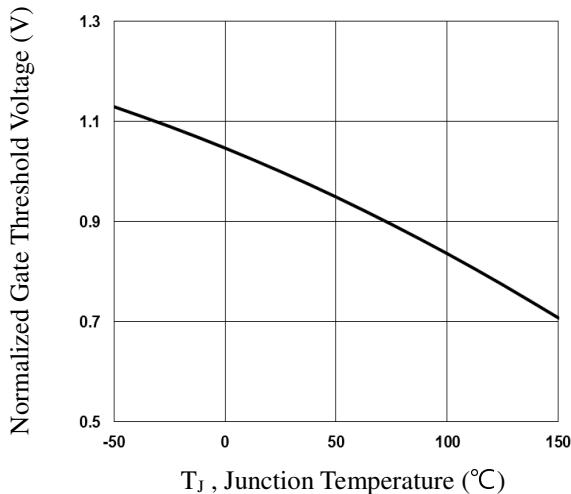
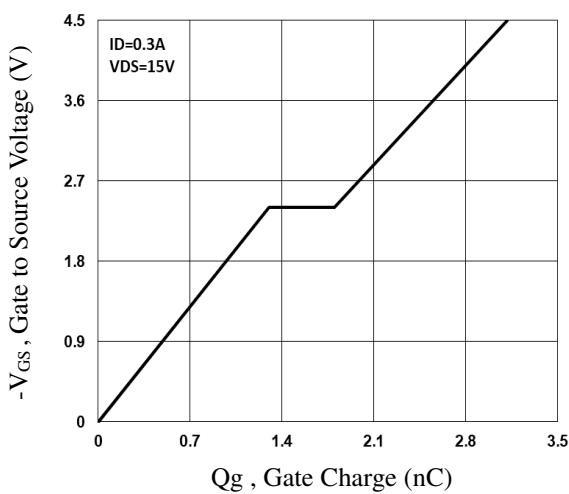
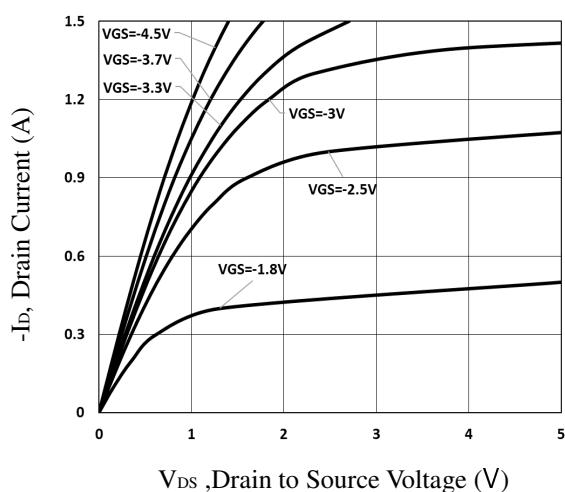
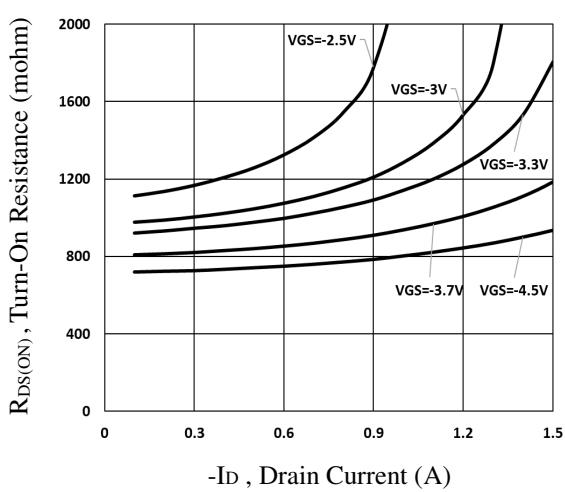
Q_g	Total Gate Charge ^{2, 3}	$V_{DS}=-15\text{V}$, $V_{GS}=-4.5\text{V}$, $I_D=-0.3\text{A}$	---	3.12	6.2	nC
Q_{gs}	Gate-Source Charge ^{2, 3}		---	1.3	2.6	
Q_{gd}	Gate-Drain Charge ^{2, 3}		---	0.5	1	
$T_{d(on)}$	Turn-On Delay Time ^{2, 3}	$V_{DD}=-15\text{V}$, $V_{GS}=-10\text{V}$, $R_G=6\Omega$ $I_D=1\text{A}$	---	7.4	15	ns
T_r	Rise Time ^{2, 3}		---	21.5	43	
$T_{d(off)}$	Turn-Off Delay Time ^{2, 3}		---	46.9	92	
T_f	Fall Time ^{2, 3}		---	14.4	29	
C_{iss}	Input Capacitance	$V_{DS}=-15\text{V}$, $V_{GS}=0\text{V}$, $F=1\text{MHz}$	---	73.4	146	pF
C_{oss}	Output Capacitance		---	19.1	38	
C_{rss}	Reverse Transfer Capacitance		---	12.1	25	

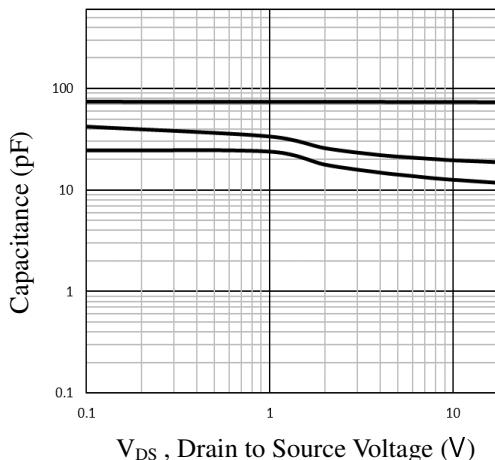
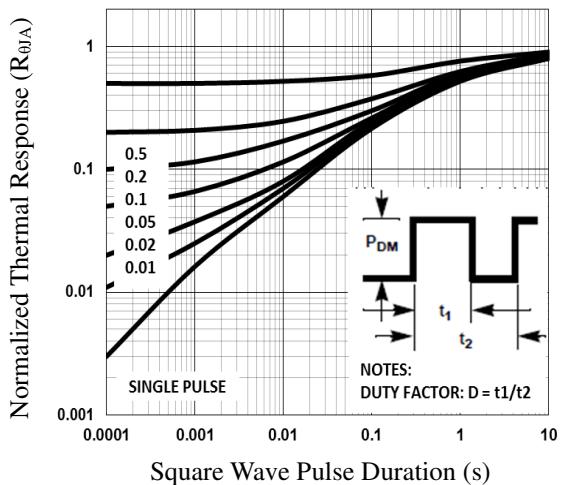
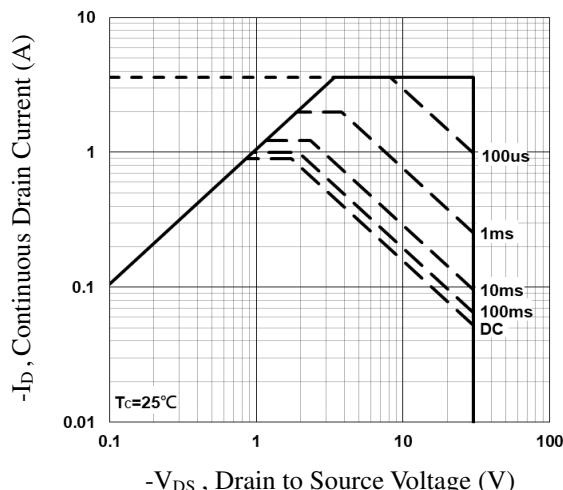
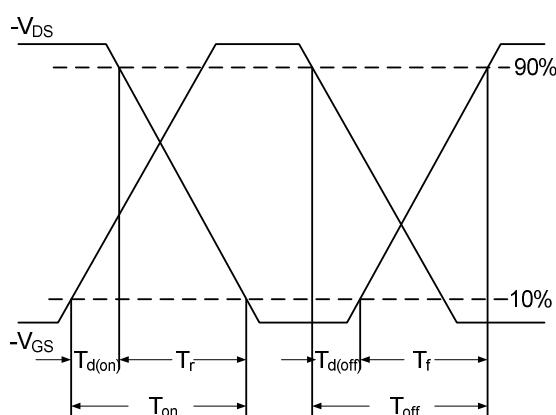
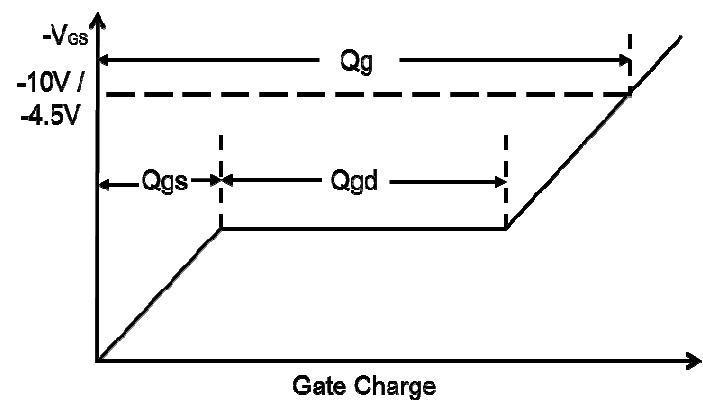
Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	-0.9	A
I_{SM}	Pulsed Source Current		---	---	-1.8	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=-0.2\text{A}$, $T_J=25\text{ }^\circ\text{C}$	---	---	-1	V
T_{rr}	Reverse Recovery Time	$VR=30\text{V}$, $IS=1\text{A}$	---	75	---	nS
Q_{rr}	Reverse Recovery Charge	$di/dt=100\text{A}/\mu\text{s}$ $T_J=25\text{ }^\circ\text{C}$	---	200	---	nC

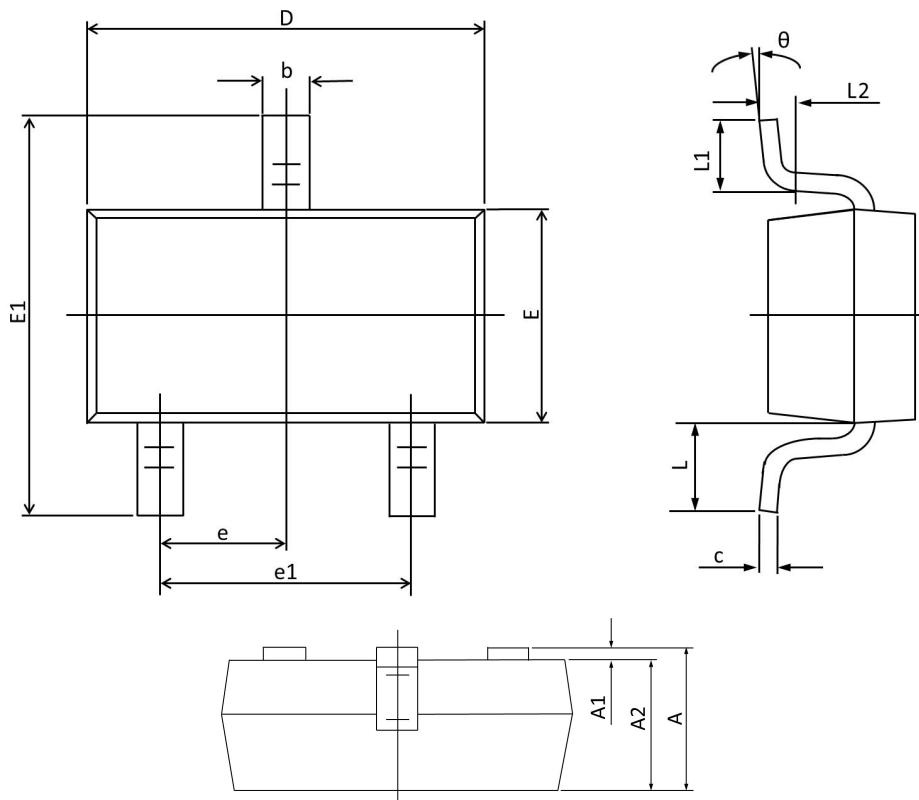
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.


Fig.1 Continuous Drain Current vs. T_J

Fig.2 Normalized RDSON vs. T_J

Fig.3 Normalized V_{th} vs. T_J

Fig.4 Gate Charge Waveform

Fig.5 Typical Output Characteristics

Fig.6 Turn-On Resistance vs. ID


Fig.7 Capacitance Characteristics

Fig.8 Normalized Transient Impedance

Fig.9 Maximum Safe Operation Area

Fig.10 Switching Time Waveform

Fig.11 Gate Charge Waveform

SOT23-3S PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Max	Min	Max	Min
A	1.150	0.900	0.045	0.035
A1	0.100	0.000	0.004	0.000
A2	1.050	0.900	0.041	0.035
b	0.500	0.300	0.020	0.012
c	0.150	0.080	0.006	0.003
D	3.000	2.800	0.118	0.110
E	1.400	1.200	0.055	0.047
E1	2.550	2.250	0.100	0.089
e	0.95 TYP.		0.037 TYP.	
e1	2.000	1.800	0.079	0.071
L	0.55 REF.		0.022 REF.	
L1	0.500	0.300	0.020	0.012
L2	0.25 TYP.		0.01 TYP.	
θ	8°	0°	8°	0°